

**THE EVALUATION ON THE EFFECT OF AGING TO THE INTERFACIAL
BONDING OF PCB SOLDERED USING SAC305**

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Final Report II

Projek Sarjana Muda

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DECLARATION

I declare that this project report entitle “The mechanical properties & microstructural analysis of welded DPS in compliance to a selected international standard” is the result of my own except as cited in the references

Signature :.....

Name :.....

Date :.....

APROVAL

I hereby declare that I have read this project report and in my opinion this report is sufficient in term of scope and quality for award of the degree of Bachelor of Mechanical Engineering (with Honours)

Signature :.....

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SUPERVISOR'S DECLARATION

I have checked this report and the report can now be submitted to JK-PSM to be delivered back to supervisor and to the second examiner.

Signature :.....

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DEDICATION

This report is dedicated to

Muhammad Shukri Bin Jaafar

Nik Salida Harlina Binti Nik Saleh

Muhammad Ziyad

Muhammad Zahin

Nur Alia'a

Fatin Atiqah

ABSTRACT

Soldering materials show evolving microstructure and mechanical behaviour that exponentially changes with environmental impacts such as isothermal aging and thermal cycling. Mechanical measurements of thermal aging effects and material behaviour development of lead-free solders were performed in the current study. For lead-free solders, 96.5Sn-3.0Ag-0.5Cu (SAC305) was characterized by isothermal aging effects and viscoplastic material developmental evolution. Isothermal aging has been performed at high temperatures (100°C, 120°C, 140°C, 160°C, 180°C and 200°C) in our total experimental program. In this paper, we focused on reporting the results of experiments resulting in temperature aging. Variations in temperature thermal aging dependent mechanical properties (micro hardness, electron microscope scanning, wettability and optical microscope) were observed and modelled as a function about 3-hour. Microstructural changes were also recorded for the solder alloys during the six temperature aging process and correlated with the observed changes in mechanical behaviour.

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TABLE OF CONTENTS

	PAGE
DECLARATION	II
APROVAL	III
SUPERVISOR'S DECLARATION	Iv
DEDICATION	v
ABSTRACT	6
ACKNOWLEDGEMENTS	7
TABLE OF CONTENTS	8
LIST OF TABLE	11
LIST OF FIGURES	12
LIST OF ABBEREVATIONS	18
LIST OF SYMBOL	19
CHAPTER	
1. INTRODUCTION	20
1.1 Background	20
1.2 Problem Statement	22
1.3 Objective	22
1.4 Scope	23
2. LITERATURE RIVIEW	24
2.1 Introduction to Soldering	24
2.2 Solder material	25
2.2.1 Lead Solder	26
2.2.2 Lead Free Solder	28
2.3 Type of Solder Profiles	32
2.3.1. Preheat stage	33
2.3.2 Thermal Soak	33
2.3.3 Reflow stage	33
2.3.4 Cool downv	34
2.4 Problem regarding soldering in electrical industry by using oxidation	35
2.5 Effect of temperature in soldering	36
2.6 Effect of aging in soldering	37

2.7 Effect of intermetallic compound in soldering	38
2.8 Application of soldering	40
3. METHODOLOGY	42
3.1 Introduction	42
3.2 Flow chart	43
3.3 Literature review	44
3.4 Sample project	44
3.5 Material	45
3.5.1 SAC 305	45
3.5.2 Printed circuit board (PCB)	46
3.6 Soldering	47
3.6.1 Step 1: Collecting material for soldering	47
3.6.2 Step 2: Preparing to solder	48
3.7 Sample preparation	49
3.8 Experimental procedure	52
3.8.1 Oven	52
3.8.2 Cold mount	52
3.8.3 Grinding and Polishing	53
3.8.4 Etching	54
3.9 Analysis	55
3.9.1 Optical Microscope (OM)	55
3.9.2 Scanning electron microscopy (SEM)	55
3.9.3 Micro hardness testing process	56
3.9.4 Wettability measurement process	57
4. RESULTS AND ANALYSIS	58
4.1 Result and Discussion	58
4.1.1 Optical microscope (OM)	58
4.1.2 Elemental analysis of the cross section using EDS	62
4.1.3 Micro hardness test on the surface of PCB using Vickers Hardness Tester	71
4.1.4 Analyse contact angle	80

5. CONCLUSION	86
5.1 Conclusion	86
5.2 Recommendation	87
REFERENCES	88
APPENDICES	91

LIST OF TABLE

TABLE	TITLE	PAGE
2.1	Thermal conductivity of solder	27
2.2	Allowable lead content in solder	28
4.1	Result of BSE on the cross section spectrum 100°C	60
4.2	Result of BSE on the cross section spectrum 120°C	61
4.3	Result of BSE on the cross section spectrum 140°C	63
4.4	Result of BSE on the cross section spectrum 160°C	64
4.5	Result of BSE on the cross section spectrum 180°C	66
4.6	Result of BSE on the cross section spectrum 200°C.	67
4.7	Result of micro hardness test on load of 980.7mN 100°C	69
4.8	Result of micro hardness test on load of 980.7mN 120°C	71
4.9	Result of micro hardness test on load of 980.7mN 140°C	72
4.10	Result of micro hardness test on load of 980.7mN 160°C	74
4.11	Result of micro hardness test on load of 980.7mN 180°C	75
4.12	Result of micro hardness test on load of 980.7mN 200°C	77
4.13	Analyse contact angle	84

LIST OF FIGURES

FIGURE	TITLE	PAGE
2.1	60/40 Tin-Lead solder	27
2.2	Solid liquid phase diagram Tin and Lead	27
2.3	Sn-Pb Phase Diagram.	28
2.4	Max Reflow Recommendations	32
2.5	SEM top surface of whole solder after reflow soldering	39
3.1	General methodology	43
3.2	Lead-free solder, SAC 305	46
3.3	PCB board	46
3.4	Solder iron	47
3.5	Soldering tools	47
3.6	The tip of the soldering iron heats both the copper pad and	50

	the lead	
3.7	The crocodile clip will reduce the heat that flows to the component	51
3.8	The solder in a good join will be shaped like a cone	51
3.9	Oven	52
3.10	Cold mount the PCB board	53
3.11	Grinding and polishing machine	53
3.12	Grinding process	54
3.13	Etching process	54
3.14	Optical microscope	55
3.15	Scanning electron microscopy	56
3.16	Vickers hardness	57
4.1	Before solder 5x	58
4.2	Before solder 10x	58
4.3	Temperature 100°C 5x	59
4.4	Temperature 100°C 10x	59
4.5	Temperature 120°C 5x	60

4.6	Temperature 120°C 10x	60
4.7	Temperature 140°C 5x	60
4.8	Temperature 140°C 10x	60
4.9	Temperature 160°C 5x	60
4.10	Temperature 160°C 10x	60
4.11	Temperature 180°C 5x	60
4.12	Temperature 180°C 10x	60
4.13	Temperature 200°C 5x	61
4.14	Temperature 200°C 10x	61
4.15	Backscattered electrons image (BSE) on the cross section spectrum 100°C	62
4.16	Graph of BSE on spectrum 100°C	62
4.17	Backscattered electrons image (BSE) on the cross section spectrum 120°C.	63
4.18	Graph of BSE on spectrum 120°C.	64
4.19	Backscattered electrons image (BSE) on the cross section spectrum 140°C.	65

4.20	Graph of BSE on spectrum 140°C	65
4.21	Backscattered electrons image (BSE) on the cross section spectrum 160°C	66
4.22	Graph of BSE on spectrum 160°C	67
4.23	Backscattered electrons image (BSE) on the cross section spectrum 180°C	68
4.24	Graph of BSE on spectrum 180°C	68
4.25	Backscattered electrons image (BSE) on the cross section spectrum 200°C	69
4.26	Graph of BSE on spectrum 200°C	70
4.27	First point 100°C	71
4.28	Second point 100°C	71
4.29	Third point 100°C	72
4.30	Fourth point 100°C	72
4.31	First point 120°C	73
4.32	Second point 120°C	73
4.33	Third point 120°C	73

4.34	Fourth point 120°C	73
4.35	First point 140°C	74
4.36	Second point 140°C	74
4.37	Third point 140°C	75
4.38	Fourth point 140°C	75
4.39	First point 160°C	76
4.40	Second point 160°C	76
4.41	Third point 160°C	76
4.42	Fourth point 160°C	76
4.43	First point 180°C	77
4.44	Second point 180°C	77
4.45	Third point 180°C	78
4.46	Fourth point 180°C	78
4.47	First point 200°C	79
4.48	Second point 200°C	79
4.49	Third point 200°C	79
4.50	Fourth point 200°C	79

4.51	Contact angle of 100°C	81
4.52	Contact angle of 120°C	81
4.53	Contact angle of 140°C	82
4.54	Contact angle of 160°C	82
4.55	Contact angle of 180°C	83
4.56	Contact angle of 200°C	83
4.57	Analyse contact angle	85

LIST OF ABBEREVATIONS

Sn	Stannum
Ag	Argentum
Cu	Copper
Pb	Lead
Au	Aurum
Bi	Bismuth
SAC	Tin, silver and copper
PCB	Printed Circuit Boards
IMC	Intermetallic compound
OM	Optical microscope
SEM	Scanning Electron Microscope
SMD	Surface mounted devices
IR	Infrared
NEMI	Electronics Manufacturing Initiative
TM	Melting temperature
ENIG	Electro less nickel immersion gold

LIST OF SYMBOL

T = Temperature

°C = Degree Celsius

μ = Micro

F = Farad

CHAPTER 1

INTRODUCTION

1.1 Background

These are quite a number of joining methods concerning microelectronics industry such as soldering, gold-to-gold interconnection and conductive film bonding. However, the versatility of soldering makes it a very commonly used and favourable joining technique for interconnections and packaging for electronics assembly. It conducts electricity between component leads and conducting wires or tracks on a printed circuit board. Solder is a metal substance having a low liquefying purpose of around 200°C. Solder is highly utilized in the electronic packaging industry to build up an electrical association between parts in the circuit by utilizing liquid metal and a soldiering iron. Solders are additionally utilized in electronic gadgets and regularly defrost at temperature underneath 350°C. (Ervina Efzan, 2015).

Printed Circuit Boards (PCB) are a basic part in relatively every electronic device. Hardware occur in an assortment of shapes and sizes which is dictated by capacity, condition and physical shape; in any event the physical gadget arrives in an assortment of shapes. The electronics part of the appliance is restricted to a standard 2.5 D approach. A printed circuit board mechanically support and electrically connects electronic components using conductive tracks, pads and other features etched from copper sheets laminated onto a non-conductive substrate. PCBs can be single sided (one copper layer), double sided (two copper layers) or multi-layer. Conductors on different layers are connected with plated-through holes called vias. Advanced PCBs may contain components - capacitors, resistors or active

devices - embedded in the substrate. (Church, 2013). The heating of the PCB fabrication must be a controlled procedure, ready to oblige segments and materials. They are four operations of the reflow profile and these segments comprise of preheat, pre flow, reflow and cooldown. (Phill Zarrow, 1990).

Tin-lead solder compounds are utilized broadly in the microelectronic manufactures. The use of tin-lead ended up well known because of its low value, high wetting properties and normal melting point temperature. However, due to the environment based legislation imposed on the usage of Tin-lead solder, efforts have been made for a Lead-free solder joint with tin silver-copper system being the most commonly used in the microelectronics industry. Tin silver-copper (Sn/ Ag/Cu) solder is generally known by the acronym "SAC". SAC solder is by and large considered as eutectic or about eutectic at a temperature of right around 217°C. Mostly, the scope of the arrangement of SAC compounds is from 0.5 to 0.8% for copper, 3.0 to 4.0% for silver, and the other remains of the arrangement is a Sn composite. (Pan, Jianbiao Wang, Jyhwen Shaddock, David M, 2005) and (Ervina Efzan, 2015)

Apart from providing the connecting and maintain its conductivity throughout the assembly, it also maintains the mechanical integrity of the solder joint. This integrity of solder joints affects the performance and the overall functioning of the assembly. The usage of electronic device has been very demanding at a considerably long period of time. This phenomenon creates thermal aging and also fatigue on the solder joint, leading to decreasing of the life span of the products. This long term reliability of solder joints is closely related to the microstructural evaluation of the intermetallic compounds (IMC) layer that formed through the migration of atoms during the reflow process with the application of heat without a thorough understanding of how the formation of IMC correspond with the aging time there are possibly that it will, lead to the failure of the solder joint.

1.2 Problem Statement

Exposing the lead-free solder joint to a temperature at considerable period can cause thermal fatigue and leave the solder joint point to corrosion which leading to failure of the joints and most probably the electronics. This long term reliability of the SAC system solder joint that subjected to thermal aging temperature of 100°C, 120°C, 140°C, 160°C, 180°C and 200°C has been associated with the formation and the characteristics of the IMC layer. This studies has been done with respect to this area but result that looks on the interfacial layer of the solder joint is still lacking.

In this particular project, the effect of thermal aging on the microstructure evolution and solder joint reliability of SAC 305 on the PCB will be investigated

1.3 Objective

The objectives of the project are as follows:

1. To determine the effect of aging temperature on the migration of copper at interfacial layer of soldering PCB.
2. To characterise the morphological aspect of the IMC developed after aging using SAC305.

1.4 Scope

The main concern in this project is to determine the effect of aging time if the migration of copper of interfacial layer of soldering PCB by looking at the microstructural evolution using optical microscope (OM) and scanning electron microscope (SEM) and to

characterise the IMC after aging using SAC305. A sample preparation will be done through metallography preparation, including mounting, grinding and polishing. The other characterization method would be sessile drop contact angle, micro hardness test and surface texture measurement.

CHAPTER 2

LITERATURE RIVIEW

2.1 Introduction to Soldering

Soldering is a method used for joining steel parts to form a mechanical or electrical bond. It commonly makes use of a low melting point steel alloy (solder) which is melted and applied to the steel parts to be joined and this bond to the metal parts and types a connection when the solder solidifies. However, most metals exposed to the atmosphere accumulate a thin film of tarnish or oxidize the longer the publicity the thicker the film will be. This film exists even although it is not visible. A soldering flux with a melting factor decrease than the solder should be used to “wet” the steel and enable the solder to penetrate it and remove the film. The flux melts first, getting rid of the tarnish or steel oxide, and also preventing in further oxide from forming while the steel is being heated to soldering temperature. The solder then melts, floating the lighter flux and the impurities suspended in it to the outer surface and edges of the molten fillet. The solder cools and forms an alloy with the metal. Most of the flux is burned away at some point of the soldering process; any residue is removed by using fabulous cleansing methods. (Wiring and Sect, 2002). Solders are also used in electronic devices and commonly thaw at temperatures under 350°C. Eutectic solder consists of 37% lead (Pb) and 63% tin (Sn). Generally, it is recognized as 63/37 solder and is desired as when it is melted, it adjustments right away from solid to liquid state. (Ervina Efzan and Siti Norfarhani, 2015).